

Intel® Wi-Fi 6E AX210 Module 2nd Generation Wi-Fi 6 with extended Wi-Fi 6E (6GHz band) support

Intel® Wi-Fi 6E AX210 (Gig+) Module

Maximize speed, latency, and reliability benefits of Wi-Fi 6 across new radio frequencies free from legacy device interference



The Intel® Wi-Fi 6E AX210 (Gig+) adapter is designed to support Wi-Fi 6E technology. The product supports dual-stream Wi-Fi in the 2.4GHz, 5GHz and 6GHz bands as well as Bluetooth® 5.3. It also supports Wi-Fi 6 R2 features, including UL MU-MIMO¹. These new features maximize the benefits of Wi-Fi 6, including Gigabit speed, ultra-low latencies, and enhanced reliability benefits across new radio frequencies exclusive to Wi-Fi 6E devices, and deliver a significant improvement in user experience in dense deployments. Combined with Intel® Core™ processors and exceptional Intel wireless innovations, the Intel® Wi-Fi 6E AX210 module can dramatically improve your connected experience at home, work, or on the go.

2nd Generation Intel Wi-Fi 6 Wireless with Extended Wi-Fi 6E (6GHz Band) Support

Greater Network Flexibility Faster Speed Reduced Latency Wi-Fi 6E Tri Band 2x2 160MHz	The Intel® Wi-Fi 6E AX210 module supports Wi-Fi 4, 5, 6, and Wi-Fi 6E, including Wi-Fi 6 R2 features. By implementing Wi-Fi 6E technology supporting the 6GHz band that includes 1200MHz of new contiguous spectrum (>2x compared to 5GHz) with more Gigabit Wi-Fi options and exclusivity to Wi-Fi 6 products, the Intel® Wi-Fi 6E AX210 module maximizes Wi-Fi 6 and Gigabit Wi-Fi benefits, enabling greater network flexibility, faster downloads, sharing and backups, as well as reduced latency and improved reliability.	
	When using Wi-Fi 6 technology with 1024QAM and 160MHz channels, the Intel® Wi-Fi 6 AX210 module can deliver nearly 3x higher peak data rates² (up to 2.4Gbps) and up to 4x capacity improvement in dense or congested environments compared to Wi-Fi 5³.	
Bluetooth® 5.3	On top of existing features, Bluetooth® 5.3 includes an Isochronous Channel feature, which lays the foundation for implementation of the next generation of Bluetooth® Audio – Low Energy Audio. The Bluetooth® 5.3 Core specification also provides the capability of changing the transmit power of the devices (local and peer) to improve the link quality while optimizing power consumption.	
Microsoft* Windows*	Full support for the latest Microsoft* Windows 10*, Windows 11* OS.	
Form Factors (M.2 2230 and 1216)	M.2 2230 modules enable system configuration and platform usage flexibility with the use of a standard Key A or Key E socket for attaching the module.	
	M.2 1216 modules enable platform design optimizations providing savings on motherboard space and BOM.	

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COMPLIANCE

Regulatory US Government

Product Safety

Experience the Intel® Diffe			
Worldwide Regulatory Support Intel® Dynamic Regulatory Solution	Enables performance-optimized worldwide regulatory compliance SKU. The Intel® Wi-Fi 6E AX210 module detects its location and automatically optimizes the Wi-Fi settings to local regulatory requirements, maximizing performance in each geography, simplifying travel experience and global enterprise procurement. Future regulatory changes are easily managed		
	during the product life cycle.		
Wireless Functionality in Pre-boot Environment	Support for Wi-Fi network and Bluetooth® Low Energy HID connectivity in the platform's UEFI (Unified Extensible Firmware Interface) environment during its boot stage. This capability enables use cases like OS recovery over Wi-Fi and Bluetooth® Low Energy-based keyboard and mouse connectivity in this pre-boot environment.		
Wirelessly Project to the Big Screen	Project your 2-in-1 or laptop content instantly, without wires, on the big HD screen with stunning image clarity and sound using Wi-Fi Miracast*. Stream movies, videos, games, photos, connect with friends, and more. Experience it all, bigger and better than ever before.		
Business-Class Wireless			
Intel® vPro® Technology4	Supports Intel's hardware-based security and management features built into Intel® Core™ vPro® processors and chipsets that enable IT to manage PCs virtually anywhere, anytime, while reducin deployment costs, improving security and ROI.		
ntel® Active Management Technology ⁵	Using integrated platform capabilities and popular third-party management and security applications, Intel® AMT allows IT or managed service providers to better discover, repair, and helprotect their networked computing assets. Intel® AMT is a feature of Intel® Core™ processors with Intel® vPro® technology.		
	lule Technical Specifications		
GENERAL			
	M.2 2230: 22mm x 30mm x 2.4mm [1.5mm Max (Top Side)/ 0.1mm Max (Bottom Side)]		
GENERAL Dimensions (H x W x D)	M.2 2230: 22mm x 30mm x 2.4mm [1.5mm Max (Top Side)/ 0.1mm Max (Bottom Side)] M.2 1216: 12mm x 16mm x 1.7 (+-0.1) mm		
GENERAL Dimensions (H x W x D)	M.2 2230: 22mm x 30mm x 2.4mm [1.5mm Max (Top Side)/ 0.1mm Max (Bottom Side)]		
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GENERAL Dimensions (H x W x D) Weight Radio ON/OFF Control	M.2 2230: 22mm x 30mm x 2.4mm [1.5mm Max (Top Side)/ 0.1mm Max (Bottom Side)] M.2 1216: 12mm x 16mm x 1.7 (+-0.1) mm M.2 2230: 2.83 +/- 0.3 g M.2 1216: 0.67 +/- 0.1 g		
GENERAL Dimensions (H x W x D) Weight Radio ON/OFF Control Connector Interface Operating Temperature	M.2 2230: 22mm x 30mm x 2.4mm [1.5mm Max (Top Side)/ 0.1mm Max (Bottom Side)] M.2 1216: 12mm x 16mm x 1.7 (+-0.1) mm M.2 2230: 2.83 +/- 0.3 g M.2 1216: 0.67 +/- 0.1 g Supported		
GENERAL Dimensions (H x W x D) Weight Radio ON/OFF Control Connector Interface Operating Temperature (Adapter Shield)	M.2 2230: 22mm x 30mm x 2.4mm [1.5mm Max (Top Side)/ 0.1mm Max (Bottom Side)] M.2 1216: 12mm x 16mm x 1.7 (+-0.1) mm M.2 2230: 2.83 +/- 0.3 g M.2 1216: 0.67 +/- 0.1 g Supported M.2: PCle*, USB		
GENERAL Dimensions (H x W x D) Weight Radio ON/OFF Control Connector Interface Operating Temperature (Adapter Shield) Humidity Non-Operating	M.2 2230: 22mm x 30mm x 2.4mm [1.5mm Max (Top Side)/ 0.1mm Max (Bottom Side)] M.2 1216: 12mm x 16mm x 1.7 (+-0.1) mm M.2 2230: 2.83 +/- 0.3 g M.2 1216: 0.67 +/- 0.1 g Supported M.2: PCle*, USB 0°C to +80°C		
GENERAL Dimensions (H x W x D) Weight Radio ON/OFF Control Connector Interface Operating Temperature (Adapter Shield) Humidity Non-Operating Operating Systems	M.2 2230: 22mm x 30mm x 2.4mm [1.5mm Max (Top Side)/ 0.1mm Max (Bottom Side)] M.2 1216: 12mm x 16mm x 1.7 (+-0.1) mm M.2 2230: 2.83 +/- 0.3 g M.2 1216: 0.67 +/- 0.1 g Supported M.2: PCle*, USB 0°C to +80°C 50% to 90% RH non-condensing (at temperatures of 25°C to 35°C)		
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GENERAL Dimensions (H x W x D) Weight Radio ON/OFF Control Connector Interface Operating Temperature (Adapter Shield) Humidity Non-Operating Operating Systems Wi-Fi Alliance ⁶	M.2 2230: 22mm x 30mm x 2.4mm [1.5mm Max (Top Side)/ 0.1mm Max (Bottom Side)] M.2 1216: 12mm x 16mm x 1.7 (+-0.1) mm M.2 2230: 2.83 +/- 0.3 g M.2 1216: 0.67 +/- 0.1 g Supported M.2: PCle*, USB O°C to +80°C 50% to 90% RH non-condensing (at temperatures of 25°C to 35°C) Microsoft* Windows 11*, Microsoft* Windows 10*, Linux* Wi-Fi CERTIFIED* 6 with Wi-Fi 6E, Wi-Fi CERTIFIED* a/b/g/n/ac, WMM*, WMM*-Power Save, WPA3*, PMF*, Wi-Direct*, Wi-Fi Agile Multiband*, Wi-Fi Location R2 HW readiness ⁷		
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GENERAL Dimensions (H x W x D) Weight Radio ON/OFF Control Connector Interface Operating Temperature (Adapter Shield) Humidity Non-Operating Operating Systems Wi-Fi Alliance ⁶ IEEE WLAN Standard	M.2 2230: 22mm x 30mm x 2.4mm [1.5mm Max (Top Side)/ 0.1mm Max (Bottom Side)] M.2 1216: 12mm x 16mm x 1.7 (+-0.1) mm M.2 2230: 2.83 +/- 0.3 g M.2 1216: 0.67 +/- 0.1 g Supported M.2: PCle*, USB 0°C to +80°C 50% to 90% RH non-condensing (at temperatures of 25°C to 35°C) Microsoft* Windows 11*, Microsoft* Windows 10*, Linux* Wi-Fi CERTIFIED* 6 with Wi-Fi 6E, Wi-Fi CERTIFIED* a/b/g/n/ac, WMM*, WMM*-Power Save, WPA3*, PMF*, Wi-Direct*, Wi-Fi Agile Multiband*, Wi-Fi Location R2 HW readiness ⁷ IEEE 802.11-2020 and select amendments (selected feature coverage) IEEE 802.11az HW readiness ⁸		
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For a list of country approvals, please contact your local Intel representatives.

FIPS⁹ 140-2

UL, C-UL, CB (IEC 60950-1)

Product Name	Model Number	Version
Intel® Wi-Fi 6E AX210	AX210NGW AX210D2W	Wi-Fi 6E (6GHz), 2x2, Bluetooth® 5.3, M.2 2230 Wi-Fi 6E (6GHz), 2x2, Bluetooth® 5.3, M.2 1216

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- ¹ Wi-Fi 6 Uplink Multi-User MIMO (Multiple Input Multiple Output) supports up to 8 streams of UL data from multiple stations improving UL network capacity in dense environment.
- 2 "Nearly 3x higher peak data rates" Intel® Wi-Fi 6 AX claims are based on the comparison of the expected maximum theoretical data rates for similarly configured 802.11ax and standard 802.11ac Wi-Fi solutions as documented in IEEE 802.11ax D4.0 spec and IEEE 802.11 wireless standard specifications, and require the use of similarly configured 802.11ax wireless network routers.
- ³ Wi-Fi 5 = 802.11ac. In accordance with the IEEE 802.1ax PAR. For additional details visit: https://mentor.ieee.org/802.11/dcn/14/11-14-0165-01-0hew-802-11-hew-sg-proposed-par.docx.
- ⁴ Intel® vPro® Technology is sophisticated and requires setup and activation. Availability of features and results will depend upon the setup and configuration of your hardware, software and IT environment. To learn more visit: http://www.intel.com/technology/vpro.
- Requires activation and a system with a corporate network connection, an Intel® AMT-enabled chipset, network hardware and software. For notebooks, Intel® AMT may be unavailable or limited over a host OS-based VPN, when connecting wirelessly, on battery power, sleeping, hibernating or powered off. Results dependent upon hardware, setup and configuration. For more information, visit http://www.intel.com/technology/platform-technology/intel-amt.
- ⁶ Support of Wi-Fi Alliance certifications is OS-dependent.
- IEEE 802.11az hardware readiness per expected Wi-Fi Location R2 feature support and based on draft 2.1 of the IEEE802.11az amendment and is subject to change.
- Some security solutions may not be supported by your device operating system and/or by your device manufacturer or may require additional hardware (e.g., UICC SIM card). Check with your device manufacturer for details on availability.
- ⁹ On Microsoft* Windows*.

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Estimated results were obtained prior to implementation of recent software patches and firmware updates intended to address exploits referred to as "Spectre" and "Meltdown". Implementation of these updates may make these results inapplicable to your device or system.

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